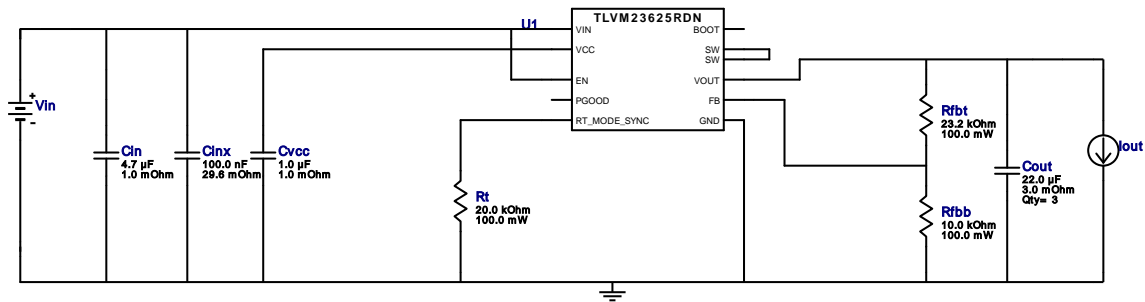


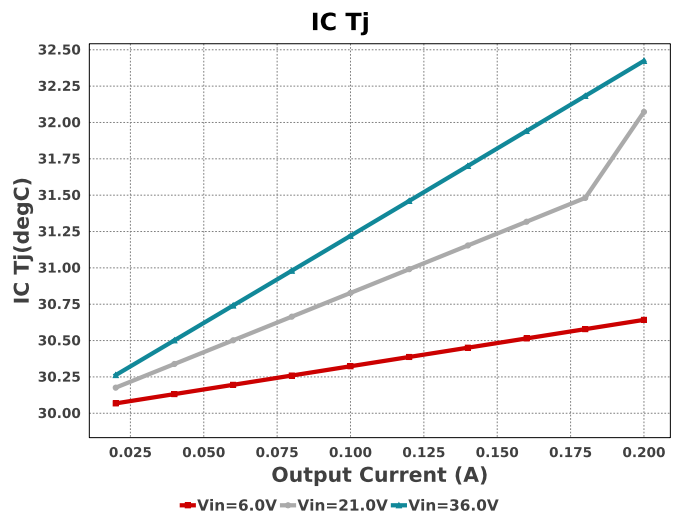
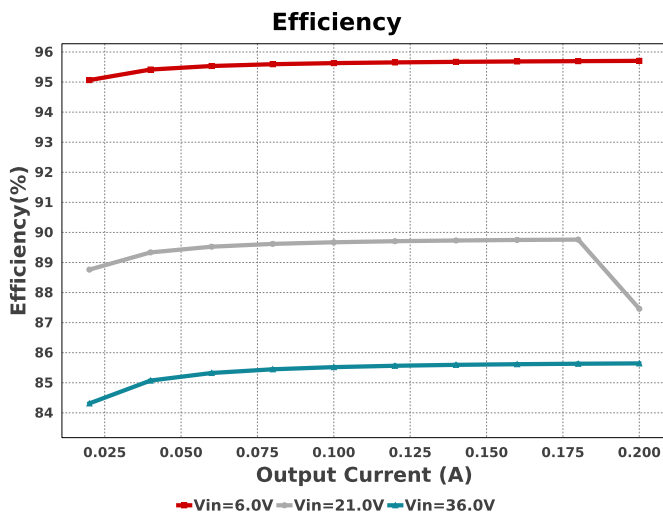
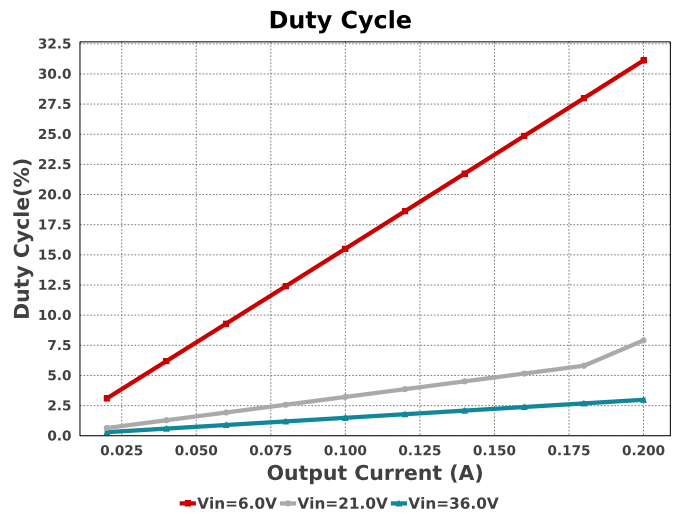
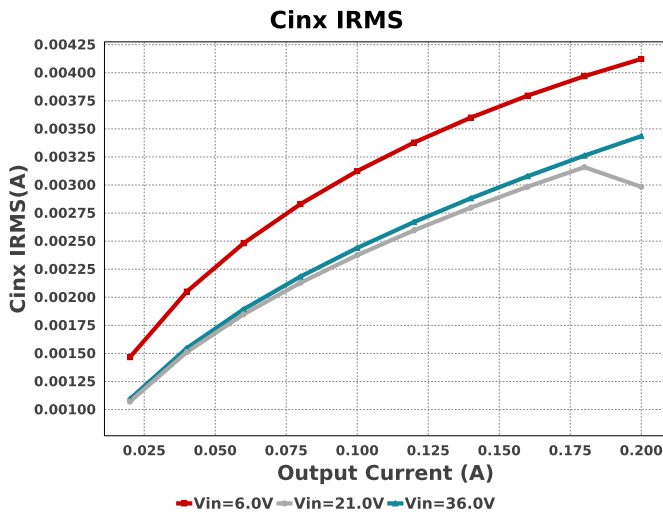
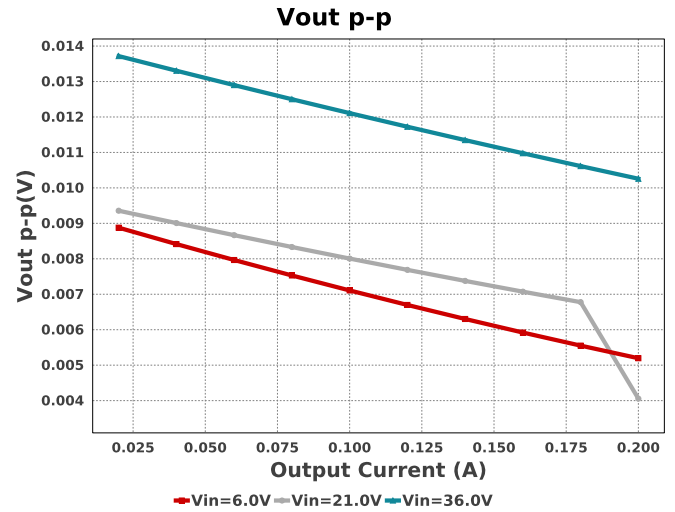
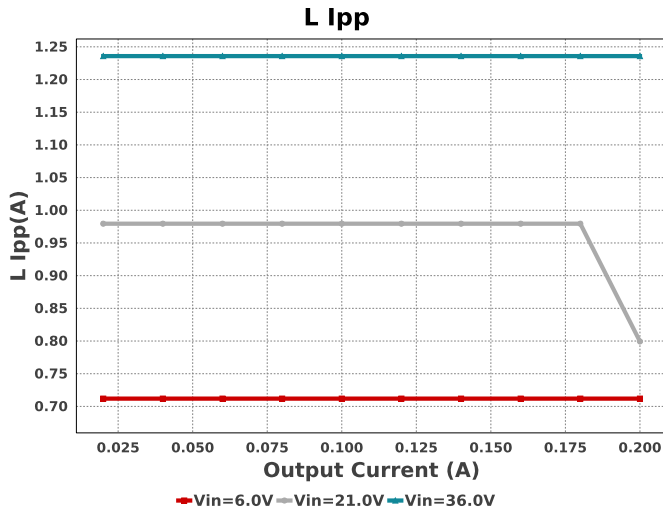
## WEBENCH® Design Report

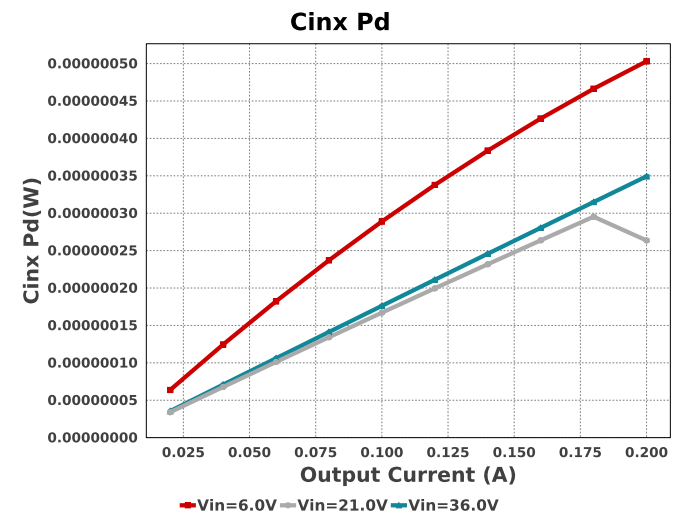
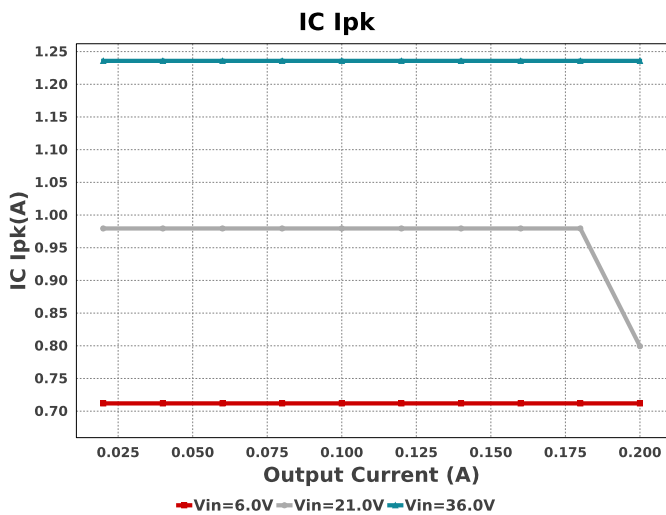
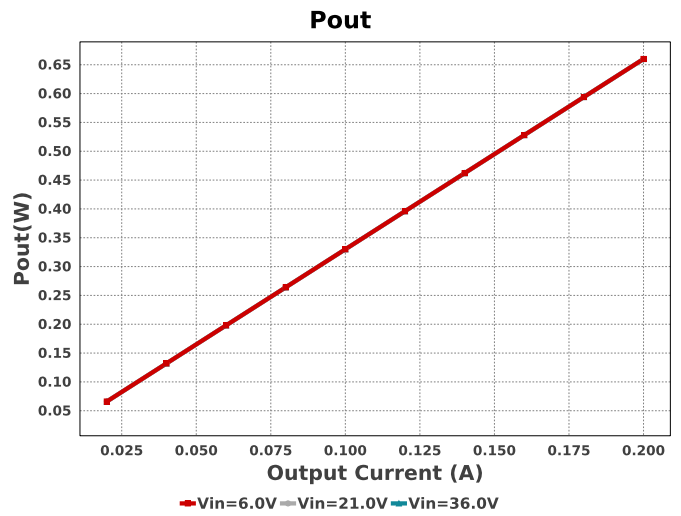
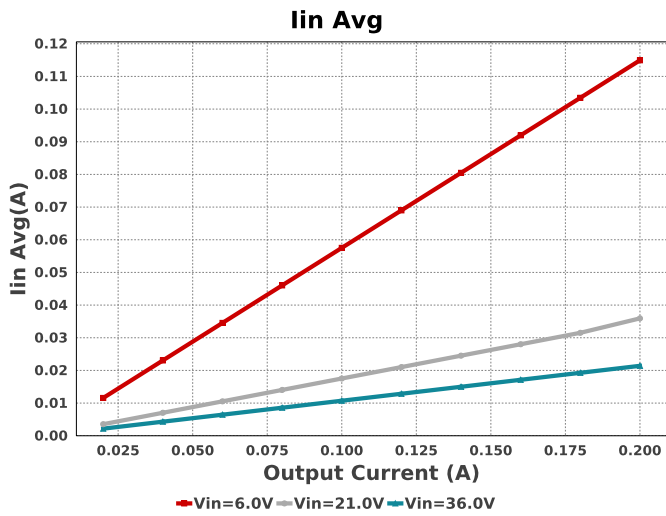
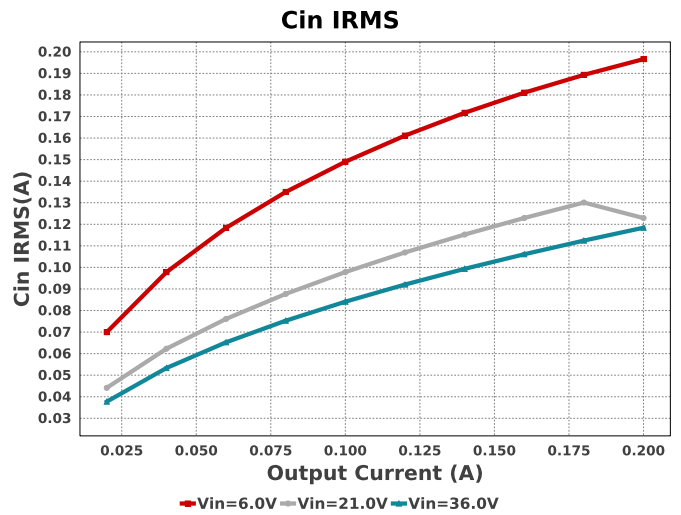
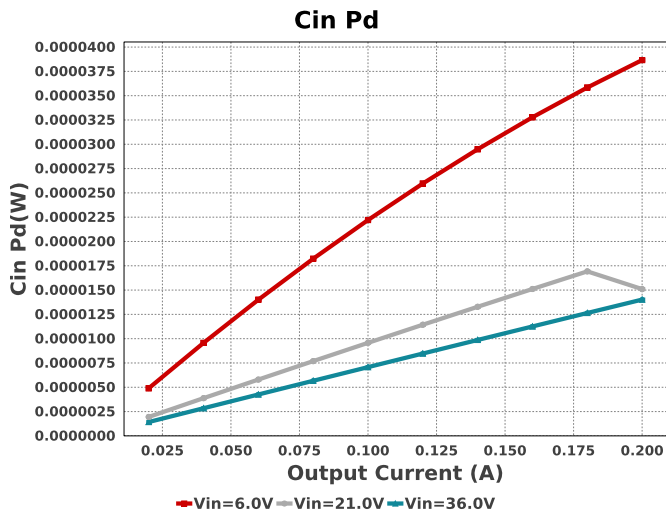
Design : 8 TLVM23625RDNR  
TLVM23625RDNR 6V-36V to 3.30V @ 0.2A

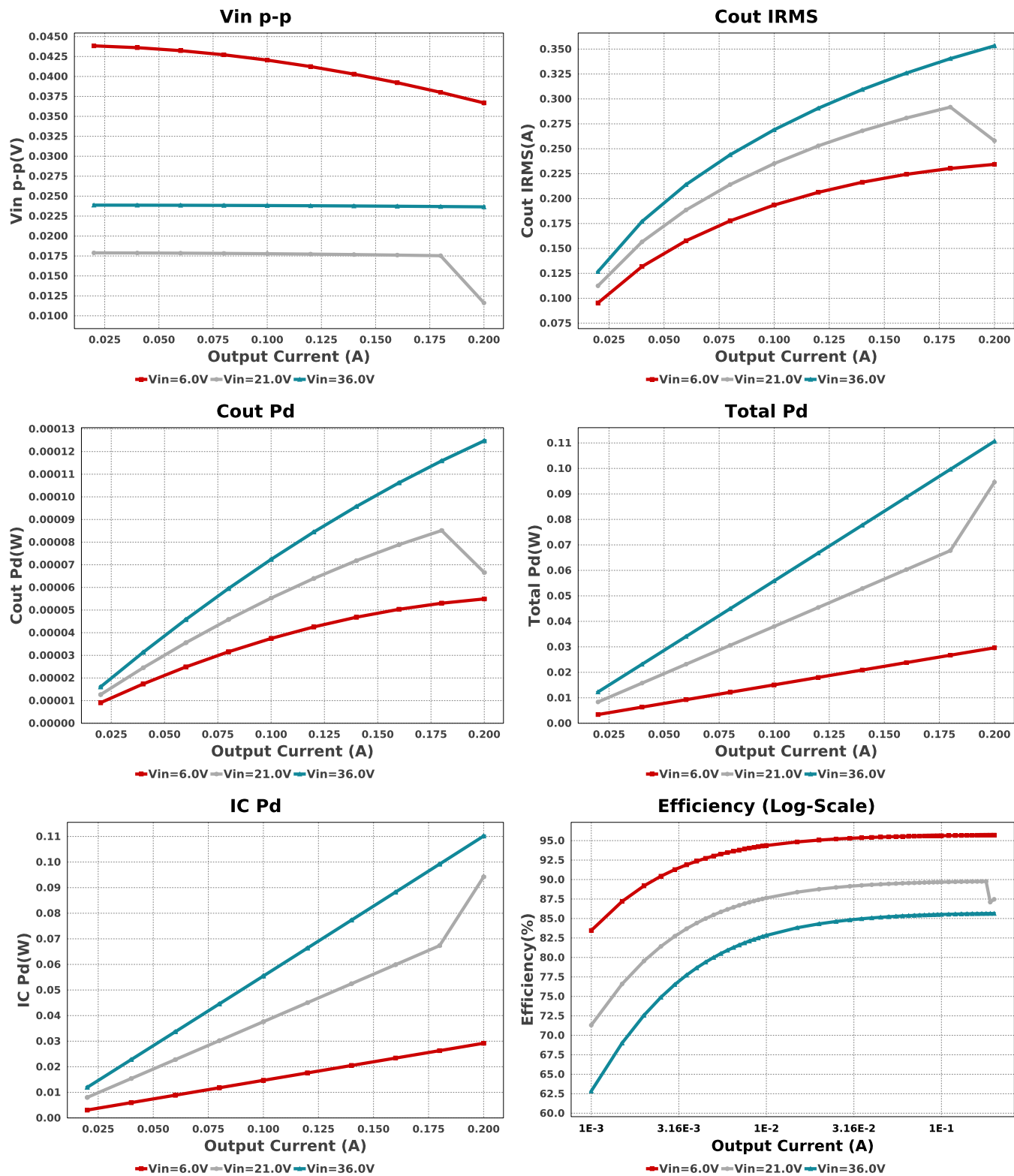


## Electrical BOM

Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Cin	MuRata	GRM32ER71H475KA88L Series= X7R	Cap= 4.7 uF ESR= 1.0 mOhm VDC= 50.0 V IRMS= 6.0 A	1	\$0.16	1210 15 mm <sup>2</sup>
Cinx	TDK	CGA3E2X7R1H104K080AA Series= X7R	Cap= 100.0 nF ESR= 29.6 mOhm VDC= 50.0 V IRMS= 971.99 mA	1	\$0.01	0603 5 mm <sup>2</sup>
Cout	MuRata	GRM21BR61A226ME44L Series= X5R	Cap= 22.0 uF ESR= 3.0 mOhm VDC= 10.0 V IRMS= 3.84 A	3	\$0.09	0805 7 mm <sup>2</sup>
Cvcc	Taiyo Yuden	EMK107B7105KA-T Series= X7R	Cap= 1.0 uF ESR= 1.0 mOhm VDC= 16.0 V IRMS= 0.0 A	1	\$0.01	0603 5 mm <sup>2</sup>
Rfbb	Yageo	RC0603FR-0710KL Series= ?	Res= 10.0 kOhm Power= 100.0 mW Tolerance= 1.0%	1	\$0.01	0603 5 mm <sup>2</sup>
Rfht	Yageo	RC0603FR-0723K2L Series= ?	Res= 23.2 kOhm Power= 100.0 mW Tolerance= 1.0%	1	\$0.01	0603 5 mm <sup>2</sup>
Rt	Vishay-Dale	CRCW060320K0FKEA Series= CRCW...e3	Res= 20.0 kOhm Power= 100.0 mW Tolerance= 1.0%	1	\$0.01	0603 5 mm <sup>2</sup>
U1	Texas Instruments	TLVM23625RDNR	Switcher	1	\$0.90	RPE0009A 9 mm <sup>2</sup>







## Operating Values

#	Name	Value	Category	Description
1.	Cin IRMS	118.41 mA	Capacitor	Input capacitor RMS ripple current
2.	Cin Pd	14.021 $\mu$ W	Capacitor	Input capacitor power dissipation
3.	Cinx IRMS	3.435 mA	Capacitor	Bulk capacitor RMS ripple current
4.	Cinx Pd	349.31 nW	Capacitor	Bulk capacitor power dissipation
5.	Cout IRMS	353.235 mA	Capacitor	Output capacitor RMS ripple current
6.	Cout Pd	124.77 $\mu$ W	Capacitor	Output capacitor power dissipation
7.	IC Ipk	1.236 A	IC	Peak switch current in IC
8.	IC Pd	110.17 mW	IC	IC power dissipation
9.	IC Tj	32.424 degC	IC	IC junction temperature
10.	IC Tolerance	12.5 mV	IC	IC Feedback Tolerance
11.	ICThetaJA Effective	22.0 degC/W	IC	Effective IC Junction-to-Ambient Thermal Resistance

#	Name	Value	Category	Description
12.	Iin Avg	21.407 mA	IC	Average input current
13.	Cin Pd	14.021 $\mu$ W	Power	Input capacitor power dissipation
14.	Cinx Pd	349.31 nW	Power	Bulk capacitor power dissipation
15.	Cout Pd	124.77 $\mu$ W	Power	Output capacitor power dissipation
16.	IC Pd	110.17 mW	Power	IC power dissipation
17.	Total Pd	110.635 mW	Power	Total Power Dissipation
18.	BOM Count	10	System	Total Design BOM count
19.	Duty Cycle	2.983 %	System	Duty cycle
20.	Efficiency	85.644 %	System	Steady state efficiency
21.	FootPrint	67.0 mm <sup>2</sup>	System	Total Foot Print Area of BOM components
22.	Frequency	358.474 kHz	System	Switching frequency
23.	Iout	200.0 mA	System	Iout operating point
24.	L Ipp	1.236 A	System	Peak-to-peak inductor ripple current
25.	Mode	PFM	System	Conduction Mode
26.	Pout	660.0 mW	System	Total output power
27.	Total BOM	\$1.38	System	Total BOM Cost
28.	Vin	36.0 V	System	Vin operating point
29.	Vin p-p	23.656 mV	System	Peak-to-peak input voltage
30.	Vout	3.3 V	System	Operational Output Voltage
31.	Vout Actual	3.32 V	System	Vout Actual calculated based on selected voltage divider resistors
32.	Vout Tolerance	2.679 %	System	Vout Tolerance based on IC Tolerance (no load) and voltage divider resistors if applicable
33.	Vout p-p	10.258 mV	System	Peak-to-peak output ripple voltage

## Design Inputs

Name	Value	Description
Iout	200.0 m	Maximum Output Current
VinMax	36.0	Maximum input voltage
VinMin	6.0	Minimum input voltage
Vout	3.3	Output Voltage
base_pn	TLVM23625	Base Product Number
source	DC	Input Source Type
Ta	30.0	Ambient temperature

## WEBENCH® Assembly

### Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of  $C_{in}$  and  $C_{out}$ , and the inductance and DC resistance of  $L1$  before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

### Soldering Component to Board

If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab down to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

### Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 6.0V and set the input supply's current limit to zero. With the input supply off connect up the input supply to  $V_{in}$  and GND. Connect a digital volt meter and a load if needed to set the minimum load of the design from  $V_{out}$  and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

### Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between  $V_{in}$  and GND, a load is connected between  $V_{out}$  and GND and a current meter is connected in series between  $V_{out}$  and the load. The load must be able to handle at least rated output power + 50% ( 7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.



### Design Assistance

1. Master key : B4595A2ED972AD82A2249E6AFD032C2A[v1]
2. **TLVM23625** Product Folder : <http://www.ti.com/product/TLVM23625> : contains the data sheet and other resources.

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